

**IN THE CLAIMS:**

1. (Currently Amended) A physical vapor deposition chamber for depositing material on a wafer, comprising:

~~a chuck comprising a planar upper surface and sidewalls extending downwardly therefrom;~~

and

a removable, detachable pedestal slip cover comprising a first and second portion:

wherein the first portion includes a top planar surface contactable with a planar backside of the wafer during material deposition on the wafer in the physical vapor deposition chamber and a chuck cavity on a side opposite the top planar surface for receiving the chuck therein; and

wherein the surface of the second portion is overlying the planar upper surface of the  
~~chuck and extending laterally beyond the sidewalls and below the planar upper surface along~~  
~~a portion of the sidewall providing a slippable detachment of the slip cover, the removable,~~  
~~detachable pedestal slip cover having a first planar surface and a second planar surface~~  
~~parallel to and located below the top planar first surface of the first portion and includes the~~  
~~removable, detachable pedestal slip cover having a peripheral circumferential groove in an~~  
~~upper surface of the second surface and a concave lower surface for receiving the planar~~  
~~upper surface of the chuck therein, wherein a circumference of the [[a ]]wafer when~~  
~~positioned on the removable, detachable pedestal slip cover chuck extends radially inwardly~~  
~~of an inner sidewall of the groove; and~~  
  
~~wherein a planar backside of the wafer is in contact with a planar upper surface of the~~  
~~removable, detachable pedestal slip cover during material deposition.~~

2. (Currently Amended) The physical vapor deposition chamber of claim 1 wherein the pedestal cover further comprises a plurality of pads on the top planar an upper surface of the first portion of the removable pedestal cover thereof, such that the wafer may be disposed on the plurality of pads

3. (Original) The physical vapor deposition chamber of claim 1 further comprising an aluminum target for depositing aluminum on the wafer.

4. (Previously Presented) The physical vapor deposition chamber of Claim 1, wherein the groove has a width and a depth and the width is greater than the depth.

5. (Currently Amended) The physical vapor deposition chamber of claim 4 wherein the pedestal cover further comprises a plurality of pads on the top first planar surface of the first portion of the removable pedestal cover, such that the wafer may be disposed on the plurality of pads.

Claims 6-7. (Canceled)

8. (Previously Presented) The physical vapor deposition chamber of claim 1 wherein a material of the pedestal cover comprises stainless steel.

9. (Previously Presented) The physical vapor deposition chamber of claim 1 wherein the material of the material deposition process is deposited on the pedestal cover during the material deposition process and is removable therefrom.

Claims 10-13. (Canceled)

14. (Withdrawn) A process for depositing material on a wafer;  
providing a chuck;  
disposing a pedestal cover over an upper surface of the chuck, the cover defining a peripheral circumferential trench therein;  
disposing a wafer in contact with an upper surface of the cover, the trench spaced radially outwardly from a circumference of the wafer; and  
depositing material on the wafer during which material is deposited in the trench.